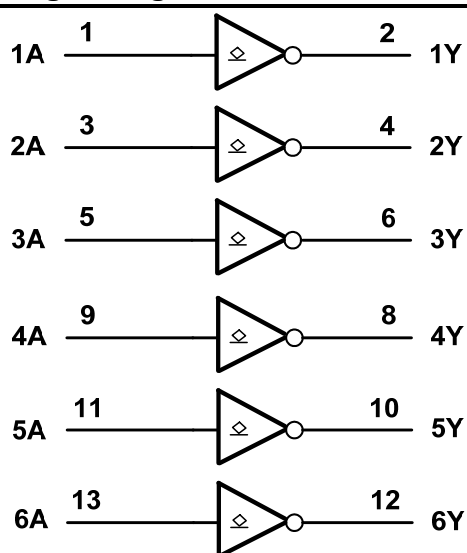


Pin Descriptions

Pin Number	Pin Name	Function
1	1A	Data Input
2	1Y	Data Output
3	2A	Data Input
4	2Y	Data Output
5	3A	Data Input
6	3Y	Data Output
7	GND	Ground
8	4Y	Data Output
9	4A	Data Input
10	5Y	Data Output
11	5A	Data Input
12	6Y	Data Output
13	6A	Data Input
14	V _{CC}	Supply Voltage

Logic Diagram



Function Table

Input	Output
A	Y
H	L
L	Z

Absolute Maximum Ratings (Note 4) (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)

Symbol	Description	Rating	Unit
ESD HBM	Human Body Model ESD Protection	2	KV
ESD CDM	Charged Device Model ESD Protection	1	KV
ESD MM	Machine Model ESD Protection	200	V
V_{CC}	Supply Voltage Range	-0.5 to +7.0	V
V_I	Input Voltage Range (Note 5)	-0.5 to +7.0	V
I_{IK}	Input Clamp Current $V_I < -0.5\text{V}$ or $V_I > V_{CC} + 0.5\text{V}$	± 20	mA
I_{OK}	Output Clamp Current $V_O < -0.5\text{V}$ or $V_O > V_{CC} + 0.5\text{V}$	± 20	mA
I_O	Continuous Output Current $-0.5\text{V} < V_O < V_{CC} + 0.5\text{V}$	+/- 25	mA
I_{CC}	Continuous Current Through V_{CC}	50	mA
I_{GND}	Continuous Current Through GND	-50	mA
T_J	Operating Junction Temperature	-40 to +150	$^\circ\text{C}$
T_{STG}	Storage Temperature	-65 to +150	$^\circ\text{C}$
P_{TOT}	Total Power Dissipation	500	mW

- Notes:
- Stresses beyond the absolute maximum may result in immediate failure or reduced reliability. These are stress values and device operation should be within recommend values.
 - Input Voltage cannot exceed V_{CC} to the extent the Maximum clamp current is exceeded

Recommended Operating Conditions (Note 6) (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)

Symbol	Parameter	Conditions	Min	Max	Unit
V_{CC}	Supply Voltage		2.0	6.0	V
V_I	Input Voltage		0	V_{CC}	V
V_O	Output Voltage		0	V_{CC}	V
$\Delta t/\Delta V$	Input transition rise or fall rate	$V_{CC} = 2.0\text{V}$		625	ns/V
		$V_{CC} = 4.5\text{V}$		140	
		$V_{CC} = 6.0\text{V}$		85	
T_A	Operating free-air temperature		-40	+125	$^\circ\text{C}$

- Note: 6. Unused inputs should be held at V_{CC} or Ground.

Electrical Characteristics (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)

Symbol	Parameter	Test Conditions	V_{CC}	$T_A = -40^\circ\text{C}$ to $+85^\circ\text{C}$		$T_A = -40^\circ\text{C}$ to $+125^\circ\text{C}$		Unit
				Min	Max	Min	Max	
V_{IH}	High-level Input Voltage		2.0V	1.5		1.5		V
			4.5V	3.15		3.15		
			6.0V	4.2		4.2		
V_{IL}	Low-level input voltage		2.0V		0.5		0.5	V
			4.5V		1.35		1.35	
			6.0V		1.8		1.8	
V_{OL}	Low-level Output Voltage	$I_{OL} = 20\mu\text{A}$	2.0V		0.1		0.1	V
		$I_{OL} = 20\mu\text{A}$	4.5V		0.1		0.1	
		$I_{OL} = 20\mu\text{A}$	6.0V		0.1		0.1	
		$I_{OL} = 4\text{mA}$	4.5V		0.33		0.44	
		$I_{OL} = 5.2\text{mA}$	6.0V		0.33		0.44	
I_{OZ}	Z State Leakage Current	$V_O = 0$ to 6.0V $V_I = \text{GND}$ or 6.0V	6.0V		± 5.0		± 10	μA
I_I	Input Current	$V_I = \text{GND}$ to 5.5V	6.0V		± 1		± 1	μA
I_{CC}	Supply Current	$V_I = \text{GND}$ or V_{CC} , $I_O = 0$	6.0V		20		40	μA

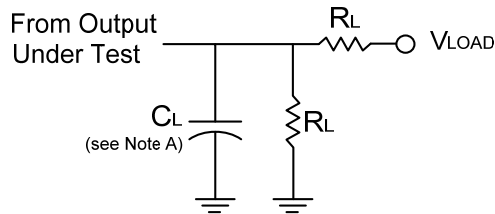
Switching Characteristics

Symbol	Parameter	Test Conditions	V _{CC}	T _A = +25°C			-40°C to +85°C	-40°C to +125°C	Unit
				Min	Typ	Max	Max	Max	
t _{PD}	Propagation Delay A _N to Y _N	Figure 1 C _L = 50 pF	2.0V	—	25	90	115	125	ns
			4.5V	—	9	18	23	27	
			6.0V	—	7	15	20	23	
t _t	Transition time	Figure 1 C _L = 50 pF	2.0V	—	19	75	95	110	ns
			4.5V	—	7	15	19	22	
			6.0V	—	6	13	16	19	

Operating Characteristics (@T_A = +25°C, unless otherwise specified.)

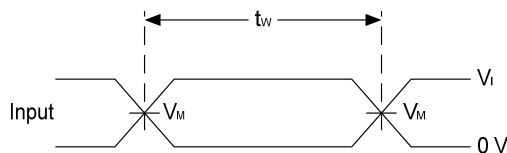
Parameter		Test Conditions	V _{CC} = 6V	Unit
			Typ	
C _{pd}	Power dissipation capacitance per gate	f = 1 MHz	22	pF
C _I	Input Capacitance	V _I = V _{CC} – or GND	4	pF

Parameter Measurement Information

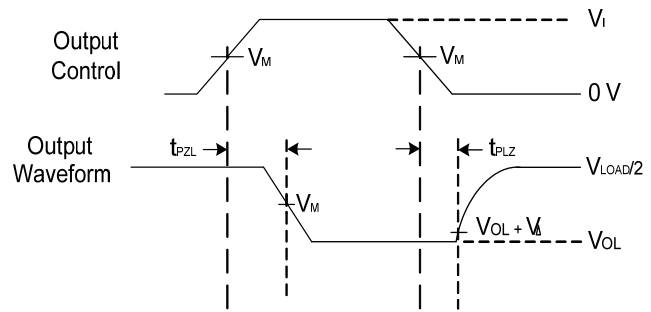


TEST	Condition
t _{PLZ} (see Notes D and E)	V _{load}
t _{PZL} (see Notes D and F)	V _{load}

V _{CC}	Inputs		V _M	V _{LOAD}	C _L	R _L	V _Δ
	V _I	t _r /t _f					
2.0V to 6.0V	V _{CC}	≤6ns	V _{CC} /2	2 X V _{CC}	50 pF	2 KΩ	10% of V _{CC}



Voltage Waveform Pulse Duration

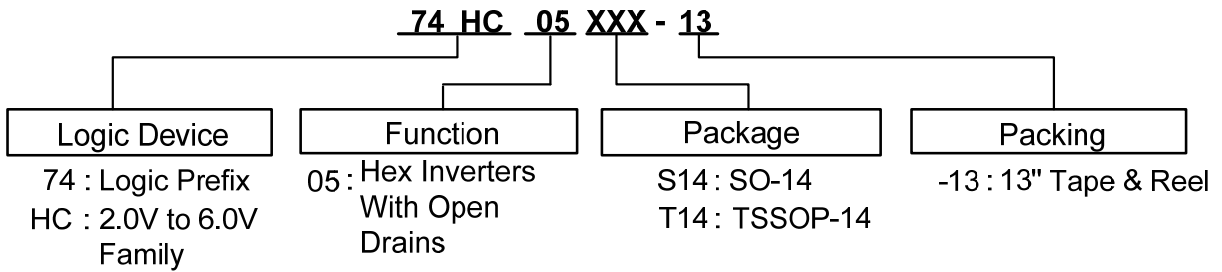


Voltage Waveform Propagation Delay Times

- Notes:
- A. Includes test lead and test apparatus capacitance.
 - B. All pulses are supplied at pulse repetition rate ≤ 1 MHz.
 - C. The inputs are measured one at a time with one transition per measurement.
 - D. For the open drain device t_{PLZ} and t_{PZL} are the same as t_{PD}.
 - E. t_{PZL} is measured at V_M.
 - F. t_{PLZ} is measured at V_{OL} + V_Δ.
 - D. A Thevenin equivalent load may be used in place of V_{CC} X 2 and resistor divider.

Figure 1 Load Circuit and Voltage Waveforms

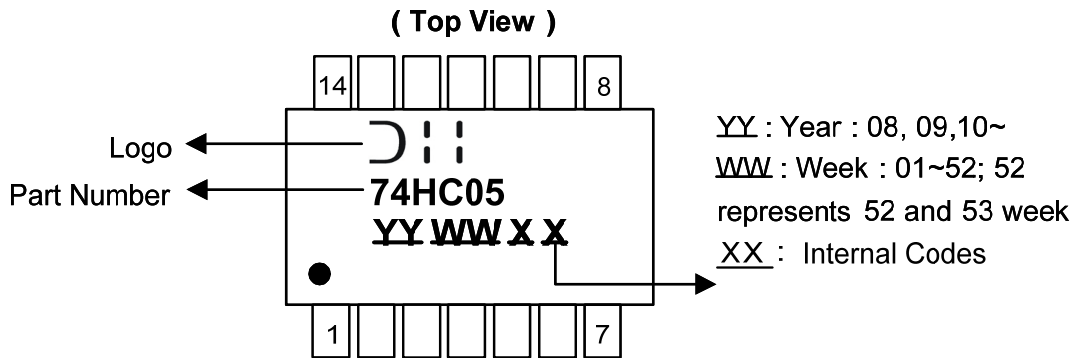
Ordering Information



Device	Package Code	Packaging	7" Tape and Reel	
			Quantity	Part Number Suffix
74HC05S14-13	S14	SO-14	2500/Tape & Reel	-13
74HC05T14-13	T14	TSSOP-14	2500/Tape & Reel	-13

Marking Information

(1) SO-14, TSSOP-14

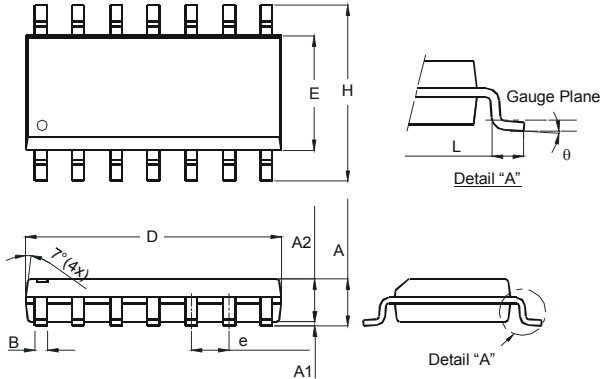


Part Number	Package
74HC05S14	SO-14
74HC05T14	TSSOP-14

Package Outline Dimensions (All dimensions in mm.)

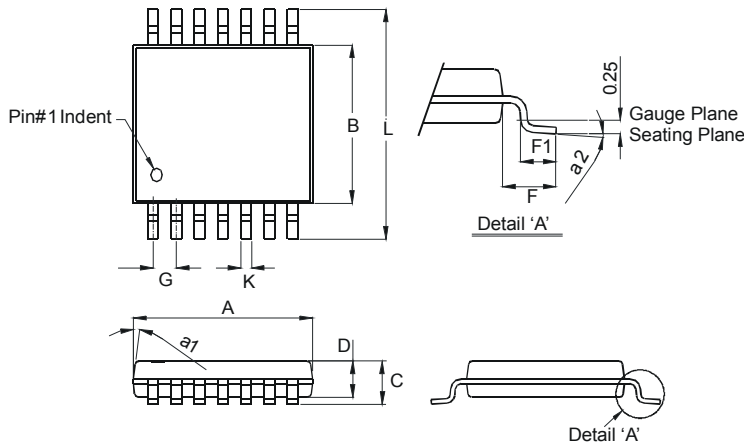
Please see AP02002 at <http://www.diodes.com/datasheets/ap02002.pdf> for latest version.

Package Type: SO-14



SO-14		
Dim	Min	Max
A	1.47	1.73
A1	0.10	0.25
A2	1.45 Typ	
B	0.33	0.51
D	8.53	8.74
E	3.80	3.99
e	1.27 Typ	
H	5.80	6.20
L	0.38	1.27
θ	0°	8°
All Dimensions in mm		

Package Type: TSSOP-14

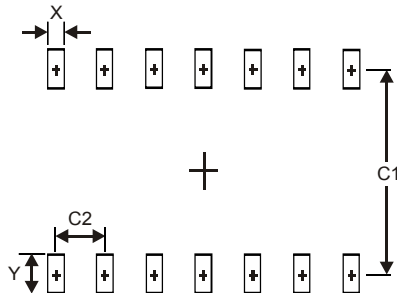


TSSOP-14		
Dim	Min	Max
a1	7° (4X)	
a2	0°	8°
A	4.9	5.10
B	4.30	4.50
C	—	1.2
D	0.8	1.05
F	1.00 Typ	
F1	0.45	0.75
G	0.65 Typ	
K	0.19	0.30
L	6.40 Typ	
All Dimensions in mm		

Suggested Pad Layout

Please see AP02001 at <http://www.diodes.com/datasheets/ap02001.pdf> for latest version.

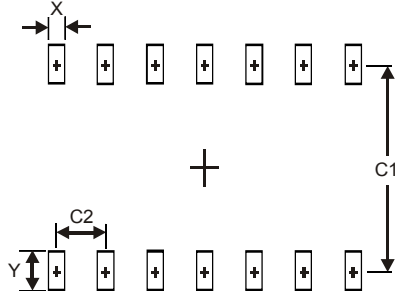
Package Type: SO-14



Dimensions	Value (in mm)
X	0.60
Y	1.50
C1	5.4
C2	1.27

Suggested Pad Layout (cont.)

Package Type: TSSOP-14



Dimensions	Value (in mm)
X	0.45
Y	1.45
C1	5.9
C2	0.65

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